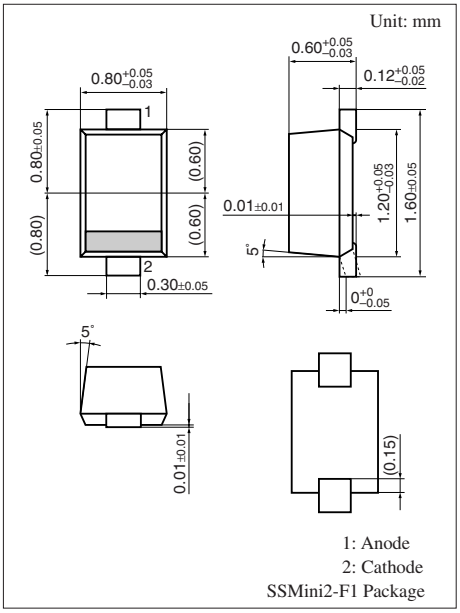
MA2SD32

Silicon epitaxial planar type

For super high speed switching

■ Features

- $I_{F(AV)}$ = 200 mA rectification is possible.
- Small reverse current: I_R < 5 µA (at V_R = 30 V)



Marking Symbol: 8H

■ Absolute Maximum Ratings T_a = 25°C

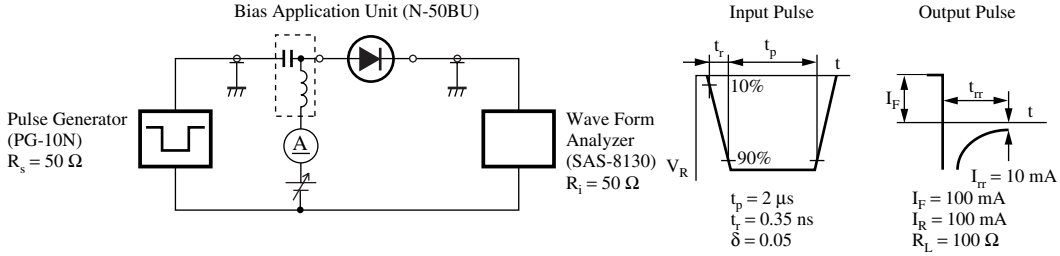
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	200	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) * : The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

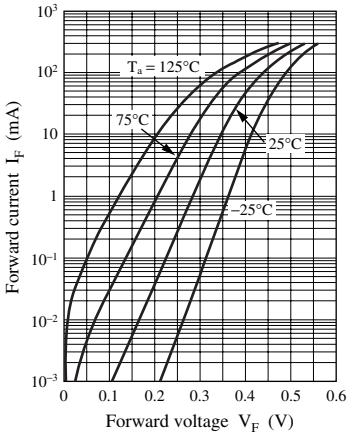
■ Electrical Characteristics T_a = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	I_{R1}	V_R = 10 V			0.5	µA
	I_{R2}	V_R = 30 V			5	
Forward voltage	V_F	I_F = 200 mA		0.49	0.56	V
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		25		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 100 mA I_{rr} = 10 mA, R_L = 100 Ω		2		ns

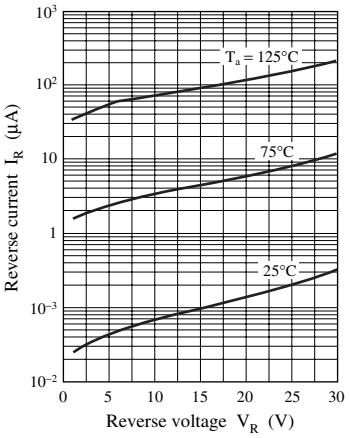
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. *: t_{rr} measurement circuit



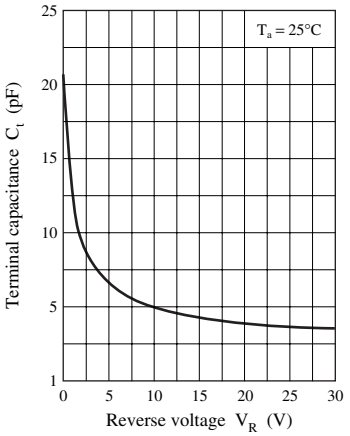
I_F — V_F



I_R — V_R



C_t — V_R



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